

Copper-coated Ceramic Substrate

Type: YZPST-DPC-16x22

- **General Description**

The copper-coated ceramic substrate uses copper plating technology, and the copper surface is protected by the copper preservative. The metal layer (copper) adheres well to the alumina ceramic substrate. The product has good heat dissipation performance .

- **Application:** Semiconductor device package insulating material

- **Features:**

	Min	Max	Units
Metal thickness	8	15	μm
Metal adhesion	Raduis of welding sopt:1.5mm Pulling force ≥ 30Kg		
Insulated withstand voltage	≧ 2500		V

- **Size: mm (±0.1)**



